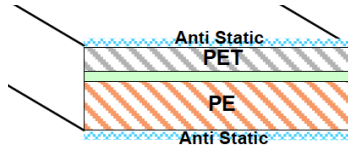


Exclusive USA / European representative
for Senawang Laminating Technologies



SL1735A ESD Clear Laminate



SL1735A is an ESD clear polyester/polyethylene laminate designed for a wide variety of applications. It is free of primary amines, amides and silicone compounds.

PHYSICAL PROPERTIES	TEST METHOD	US STANDARD	METRIC
Thickness*	ASTM D374	3.5 mil	89.0 $\mu\text{m} \pm 10\%$
Basis Weight*		53.4 lbs/ream	87.0 $\text{g/m}^2 \pm 10\%$
Yield		56.1 ft^2/lb 8081 in^2/lb	11.5 m^2/kg
Tensile Strength MD* TD*	ASTM D882	6526 psi 5511 psi	45.0 MPa 38.0 MPa
Elmendorf Tear Resistance MD* TD*	ASTM D1922		80 gf 100 gf
Graves Strength MD* TD*	ASTM D1004		900 gf 1200 gf
Spencer Impact*	ASTM D3420		3500 gf
Puncture Resistance*	FTMS 101C Method 2065	14.0 lbf	6400 gf
MVTR - Typical value	ASTM F1249 (37.8°C, 90% RH)	0.35 $\text{g}/100\text{in}^2/\text{day}$	5.4 $\text{g}/\text{m}^2/\text{day}$
Heat Seal Range	ASTM F88-99	275°F - 500°F	135°C - 260°F
Seal Strength (min.)	ASTM F88-99 (185°C, 1s, 4 bar)	> 11.0 lbf	> 5000 gf
ELECTRICAL PROPERTIES	TEST METHOD	SPECIFICATIONS	
Surface Resistance	EOS/ESD S11.11	> 1×10^5 and < $1 \times 10^{11} \Omega$	
Surface Resistivity	EOS/ESD S11.11	> $1 \times 10^6 \Omega/\text{sq}$ and < $1 \times 10^{12} \Omega/\text{sq}$	

*Average values given.

Shelf Life: The shelf life of this is one year under normal warehouse conditions. Extreme hot or cold temperatures and humidity can cause a reduction in the shelf life.

Disclaimer: The above information is presented in good faith is based on a limited number of samples taken from normal production materials. Actual test values may vary from information presented. MacPac, Inc. and Senawang Laminating Technologies Sdn. Bhd. reserve the right to change the specification at anytime without prior notification. MacPac, Inc. and Senawang Laminating Technologies Sdn. Bhd. assume no liability, expressed or implied, for fitness of use of this product in any application. Users of this material are strongly encouraged to test its fitness of use in their processes and applications.